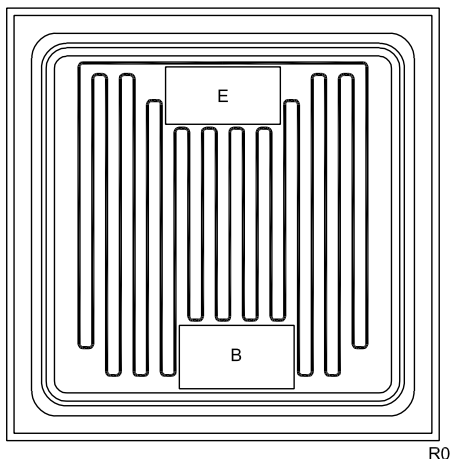


**PROCESS DETAILS**

Die Size	68 x 68 MILS
Die Thickness	8.5 MILS $\pm$ 0.6 MILS
Base Bonding Pad Area	17.7 x 10.2 MILS
Emitter Bonding Pad Area	18.1 x 8.9 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Ag - 14,000Å

**GEOMETRY**



BACKSIDE COLLECTOR

**GROSS DIE PER 4 INCH WAFER**

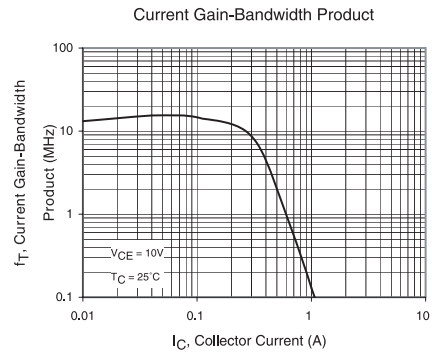
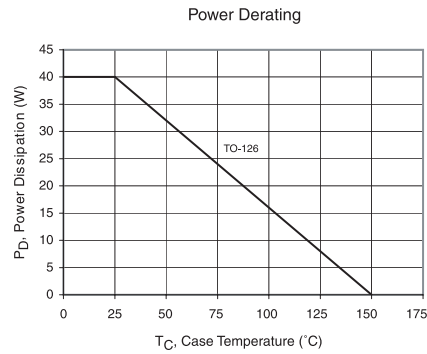
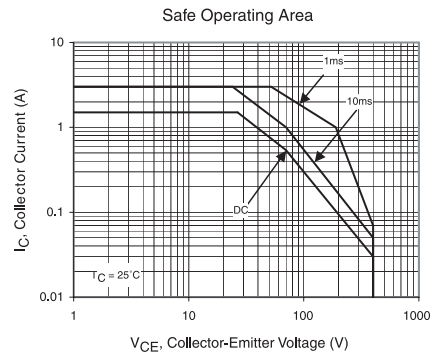
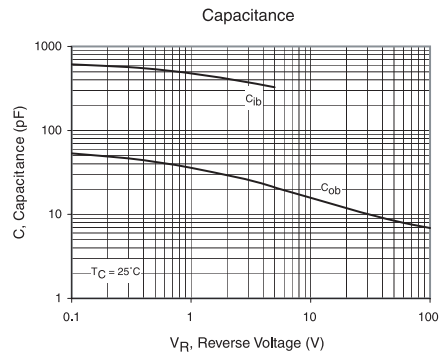
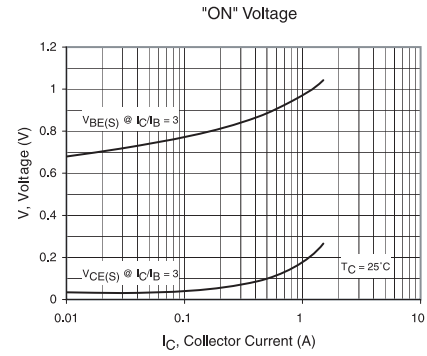
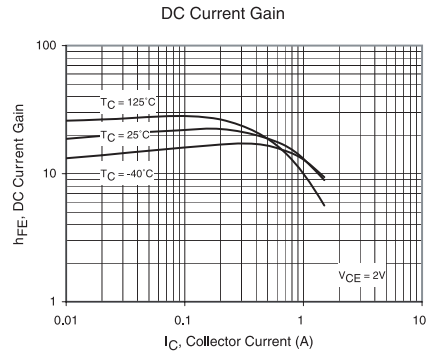
2,440

**PRINCIPAL DEVICE TYPES**

MJE13003

145 Adams Avenue  
Hauppauge, NY 11788 USA  
Tel: (631) 435-1110  
Fax: (631) 435-1824  
[www.centalsemi.com](http://www.centalsemi.com)

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